

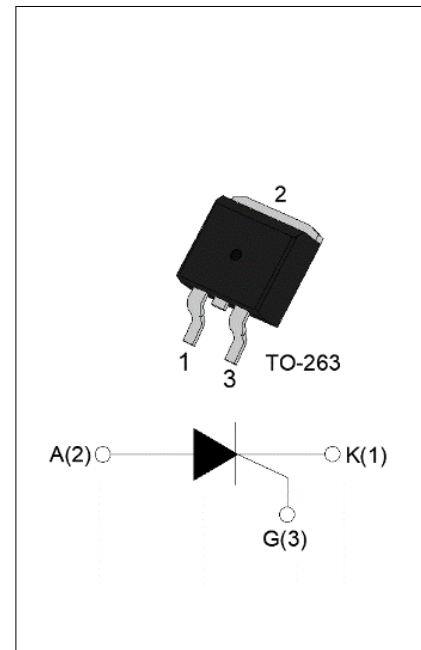


DESCRIPTION:

With high ability to withstand the shock loading of large current, JCT1625E SCR provides high dV/dt rate with strong resistance to electromagnetic interference. It is especially recommended for use on solid state relay, motorcycle, power charger, T-tools etc. Package TO-263 is RoHS compliant.

MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	25	A
V_{DRM}/V_{RRM}	1600	V
I_{GT}	≤ 40	mA



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	T_{stg}	-40-150	$^{\circ}\text{C}$
Operating junction temperature range	T_j	-40-125	$^{\circ}\text{C}$
Repetitive peak off-state voltage ($T_j=25^{\circ}\text{C}$)	V_{DRM}	1600	V
Repetitive peak reverse voltage ($T_j=25^{\circ}\text{C}$)	V_{RRM}	1600	V
Average on-state current ($T_c \leq 77^{\circ}\text{C}$)	$I_{T(AV)}$	16	A
RMS on-state current ($T_c \leq 77^{\circ}\text{C}$)	$I_{T(RMS)}$	25	A
Non repetitive surge peak on-state current ($t_p=10\text{ms}$, $T_j=25^{\circ}\text{C}$)	I_{TSM}	280	A
Non repetitive surge peak on-state current ($t_p=8.3\text{ms}$, $T_j=25^{\circ}\text{C}$)		300	
I^2t value for fusing ($t_p=10\text{ms}$, $T_j=25^{\circ}\text{C}$)	I^2t	392	A^2s
Critical rate of rise of on-state current ($I_G=2 \times I_{GT}$, $f=100\text{Hz}$, $T_j=125^{\circ}\text{C}$)	di/dt	200	$\text{A}/\mu\text{s}$
Peak gate current ($t_p=20\mu\text{s}$, $T_j=125^{\circ}\text{C}$)	I_{GM}	5	A
Average gate power dissipation ($T_j=125^{\circ}\text{C}$)	$P_{G(AV)}$	1	W

Peak gate power	P_{GM}	20	W
Peak pulse voltage ($T_j=25^{\circ}\text{C}$; non-repetitive, off-state; FIG.8)	V_{pp}	1.5	kV

ELECTRICAL CHARACTERISTICS ($T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Test Condition	Value			Unit
		MIN.	TYP.	MAX.	
I_{GT}	$V_D=12\text{V}$ $R_L=33\Omega$	-	-	40	mA
V_{GT}		-	-	1	V
V_{GD}	$V_D=V_{DRM}$ $T_j=125^{\circ}\text{C}$ $R_L=3.3\text{k}\Omega$	0.2	-	-	V
I_L	$I_G=1.2I_{GT}$	-	-	100	mA
I_H	$I_T=500\text{mA}$	-	-	90	mA
dV/dt	$V_D=1070\text{V}$ Gate Open $T_j=125^{\circ}\text{C}$	1000	-	-	V/ μs
t_{on}	$I_G=50\text{mA}$ $I_A=500\text{mA}$ $I_R=50\text{mA}$ $T_j=25^{\circ}\text{C}$	-	7	-	μs
t_{off}		-	100	-	

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX.)	Unit
V_{TM}	$I_{TM}=50\text{A}$ $t_p=380\mu\text{s}$	$T_j=25^{\circ}\text{C}$	1.8	V
V_{TO}	Threshold voltage	$T_j=125^{\circ}\text{C}$	0.74	V
R_D	Dynamic resistance	$T_j=125^{\circ}\text{C}$	27	$\text{m}\Omega$
I_{DRM}	$V_D=V_{DRM}$ $V_R=V_{RRM}$	$T_j=25^{\circ}\text{C}$	10	μA
I_{RRM}		$T_j=125^{\circ}\text{C}$	4	mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	junction to case (DC)	1.3	$^{\circ}\text{C}/\text{W}$
$R_{th(j-a)}$	junction to ambient (DC, in free air, $S=1\text{cm}^2$)	50	$^{\circ}\text{C}/\text{W}$

ORDERING INFORMATION

<u>J</u>	<u>CT</u>	<u>16</u>	<u>25</u>	<u>E</u>	<u>-/</u>
JieJie Microelectronics Co., Ltd.	SCRs			E:TO-263	Blank:Tube -TR:Tape & Reel
16: $V_{DRM}/V_{RRM} \geq 1600V$		IT(RMS):25A			

MARKING

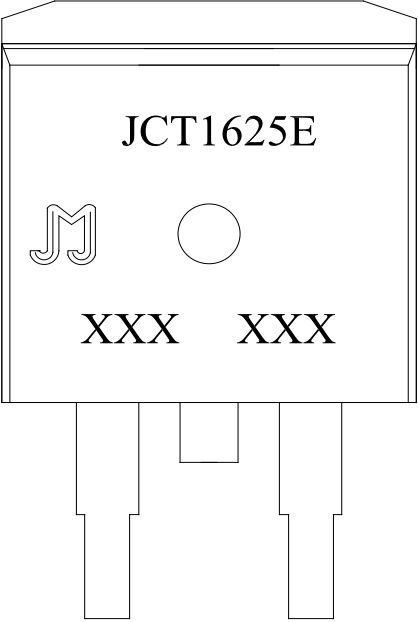
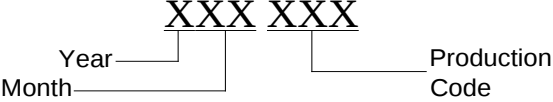
	
---	--

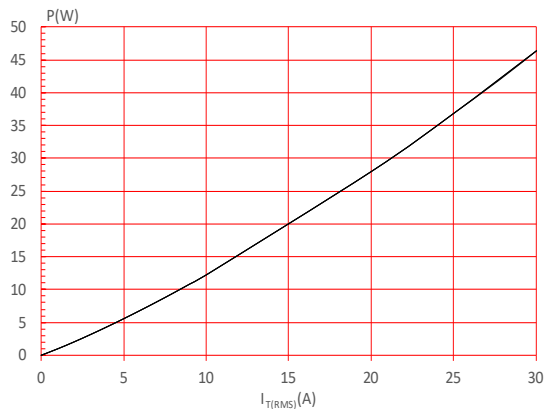
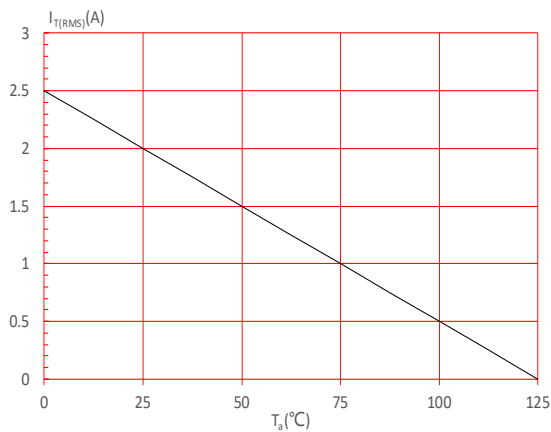
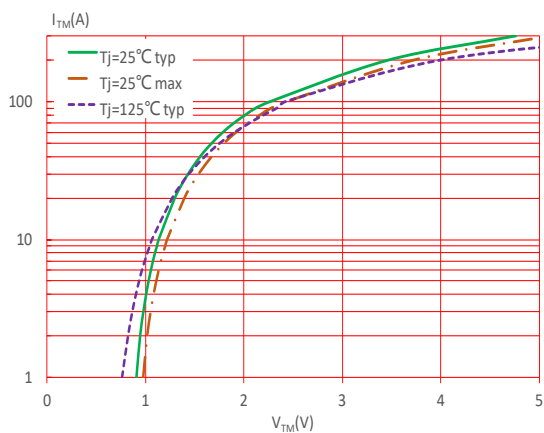
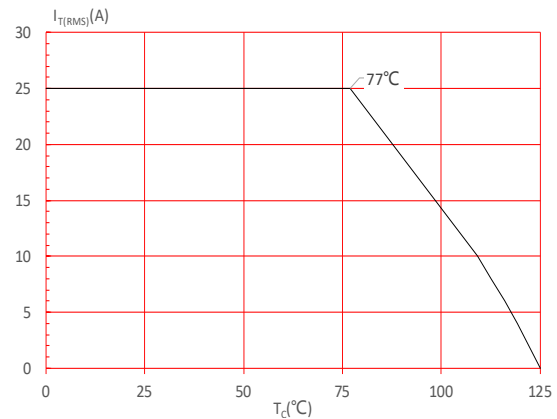
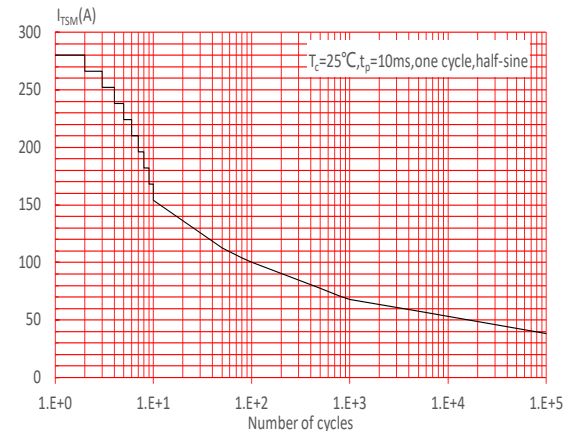
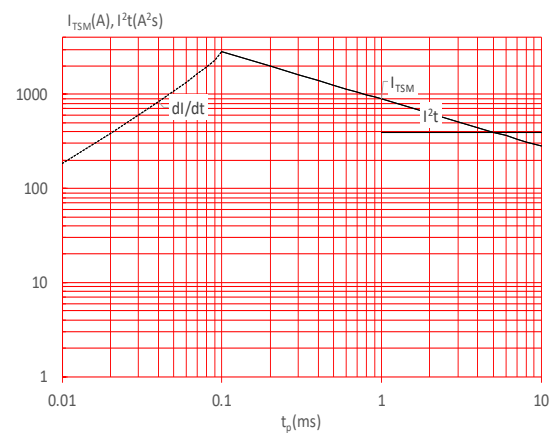
FIG.1: Maximum power dissipation versus RMS on-state current

FIG.3: RMS on-state current versus ambient temperature (printed circuit board FR4,copper thickness:35 μm)(full cycle)

FIG.5: On-state characteristics

FIG.2: RMS on-state current versus case temperature

FIG.4: Surge peak on-state current versus number of cycles

FIG.6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10ms$, and corresponding value of I^2t ($dI/dt < 200A/\mu s$)


FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature

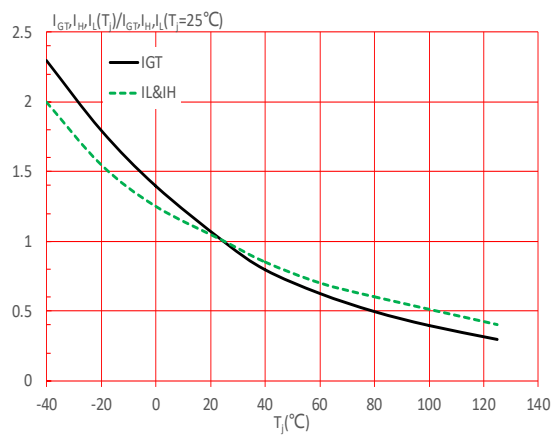
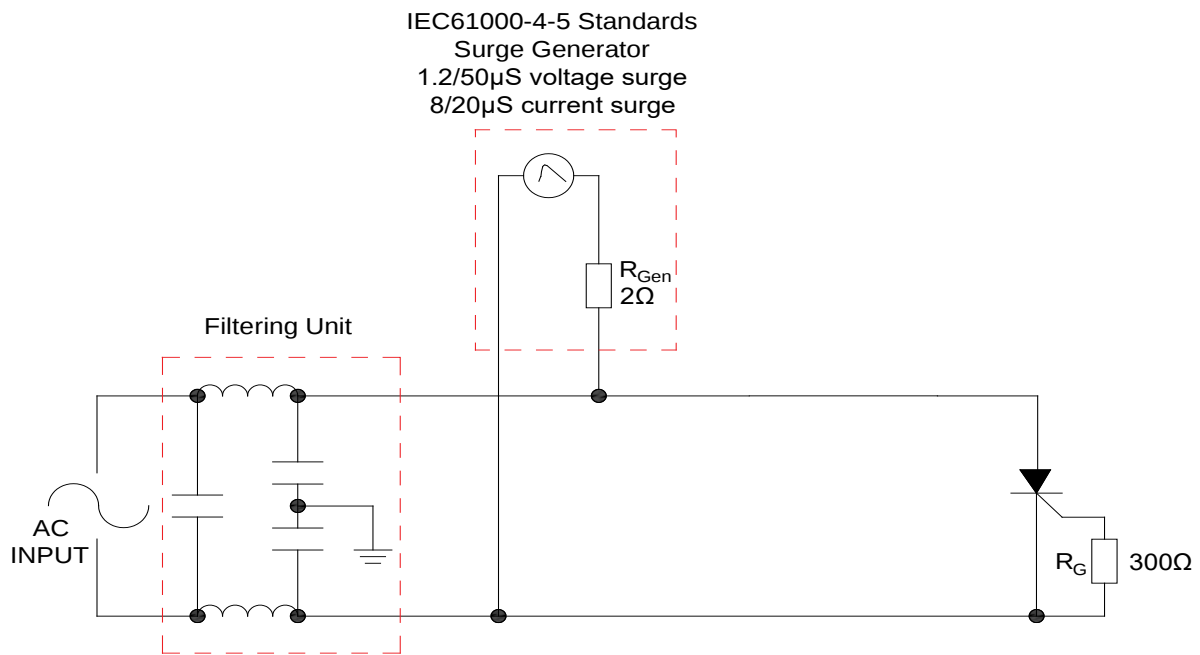
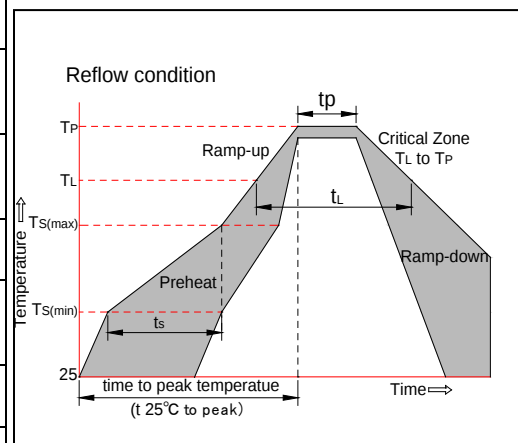


FIG.8: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards.



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



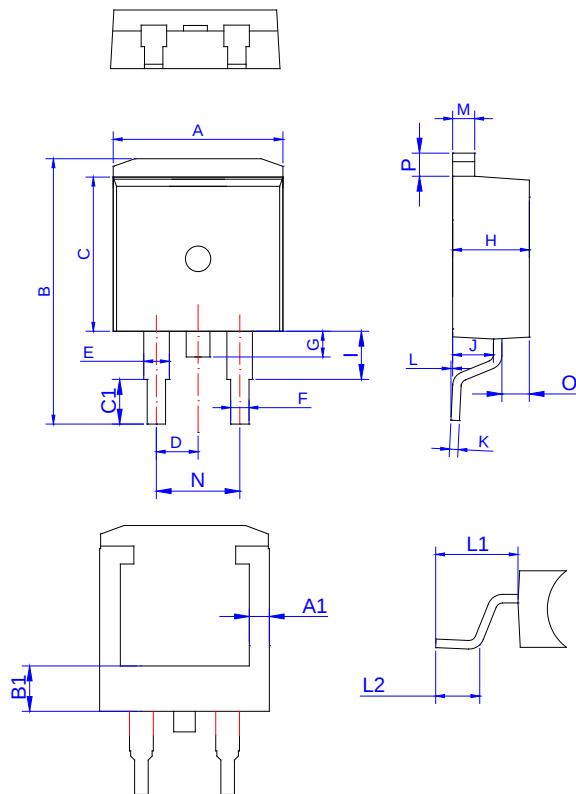
ORDERING INFORMATION

Order code	Voltage $V_{\text{DRM}}/V_{\text{RRM}}$ (V)	IGT(mA)	Package	Base qty. (pcs)	Delivery mode
JCT1625E	1600	40	TO-263	50	Tube
JCT1625E-TR				800	Tape & Reel

Document Revision History

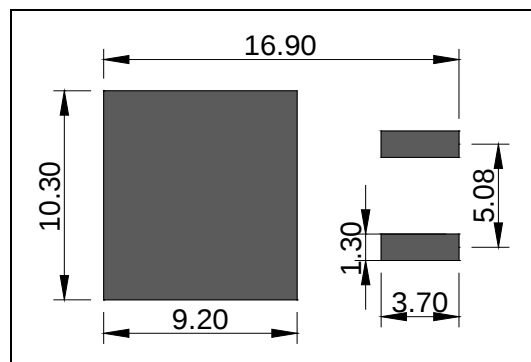
Date	Revision	Changes
May 17, 2023	A.1.0	Last update
Oct.16, 2025	A.1.1	Revise PACKAGE MECHANICAL DATA

PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
A1	0.80		1.20	0.031		0.047
B	14.70		15.80	0.579		0.622
B1	2.15		2.55	0.085		0.100
C	9.40		9.60	0.370		0.378
C1	2.40		2.80	0.094		0.110
D	2.40		2.70	0.094		0.106
E	1.20		1.50	0.047		0.059
F	0.75		0.85	0.029		0.033
G	1.00		1.50	0.039		0.059
H	4.40		4.70	0.173		0.185
I	1.80		2.20			
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
L1	4.65		5.05	0.183		0.199
L2	1.90			0.075		
M	1.25		1.35	0.049		0.053
N	4.80		5.20			
O	1.30		1.50			
P	1.20		1.50	0.047		0.059

FOOTPRINT-TO-263 (dimensions in mm)



Technical drawing of a 100mm x 100mm x 12.9mm aluminum extrusion profile. The drawing includes a top view showing a width of 530±0.5mm and a mounting hole diameter of Ø3.0mm. A side view shows a height of 173.1mm and a flange thickness of 7.0mm. The profile features a central channel and mounting tabs with dimensions 1.5mm, 0.6mm, and 2.6mm.

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	23.70	24.00	24.30	0.933	0.945	0.957
E	1.65	1.75	1.85	0.065	0.069	0.073
F	11.40	11.50	11.60	0.449	0.453	0.457
D0	-	1.50	1.60	-	0.059	0.063
D1	-	1.50	1.60	-	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	15.90	16.00	16.10	0.626	0.630	0.634
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	10.80	10.90	11.00	0.425	0.429	0.433
B0	16.20	16.30	16.40	0.638	0.642	0.646
K0	4.80	4.90	5.00	0.189	0.193	0.197
t	0.35	0.40	0.45	0.014	0.016	0.018

9

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement. Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.

 is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.
Copyright © 2025 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.